

An apparatus and method for providing gross location, planarization, and mechanical restraint to one or more electronic components such as semiconductor dice to be subjected to stereolithographic processing. A double platen assembly having a first platen and a second platen mutually removably connected and configured and arranged to substantially secure an electronic component assembly in position therebetween. At least one of the platens is configured such that a portion of electronic components of a carrier substrate secured by the double platen assembly is viewable for exposure to an energy beam such as a laser beam used to cure a liquid into an associated dielectric stereolithographic packaging structure. Another embodiment includes the use of an adhesive coated film for holding locating and securing a plurality of individual electronic components for processing. A method of forming solder balls is also disclosed.

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